

PACDN1404

ESD Protection Diode Arrays Chip Scale Package

Product Description

The PACDN1404 and PACDN1408 are 4- and 8-channel surge protection arrays that provide a very high level of protection for sensitive electronic components that may be subjected to ESD.

These devices are designed and characterized to safely dissipate ESD strikes at levels well beyond the maximum requirements set forth in the IEC 61000-4-2 international standard (Level 4, ± 8 kV contact discharge). All I/Os are rated at ± 25 kV using the IEC 61000-4-2 contact discharge method. Using the MIL-STD-883D (Method 3015) specification for Human Body Model (HBM) ESD, all pins are protected for contact discharges to greater than ± 30 kV.

The Chip Scale Package format of these devices provide extremely small footprints that are necessary in portable electronics such as cellular phones, PDAs, internet appliances and PCs. The large solder bumps allow for standard attachments to laminate boards without the use of underfill. The PACDN1404 and PACDN1408 are packaged in RoHS-compliant, lead-free finishing.

Features

- Four or Eight surge protection in a Single Package
- In-System Electrostatic Discharge (ESD) Protection to ± 25 kV Contact Discharge per IEC 61000-4-2 International Standard
- Compact Chip Scale Package (CSP) in a 0.65 mm Pitch Format Saves Board Space and Eases Layout in Space Critical Applications Compared to Discrete Solutions and Traditional Wire Bonded Packages
- 6- and 10-Bump WLCSPs
- These Devices are Pb-Free and are RoHS Compliant

Applications

- ESD Protection for Sensitive Electronic Equipment
- I/O Port, Keypad and Button Circuitry Protection for Portable Devices
- Wireless Handsets
- Handheld PCs / PDAs
- MP3 Players
- Digital Cameras and Camcorders
- Notebooks
- Desktop PCs



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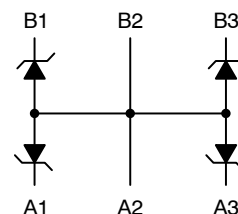


WLCSP6
CG SUFFIX
CASE 567BD

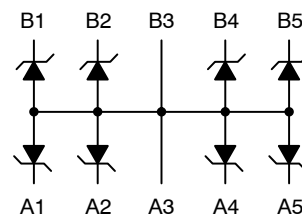


WLCSP10
CG SUFFIX
CASE 567BM

ELECTRICAL SCHEMATIC



PACDN1404



PACDN1408

MARKING DIAGRAM



D14 = PACDN1404CG
DN1408 = PACDN1408CG

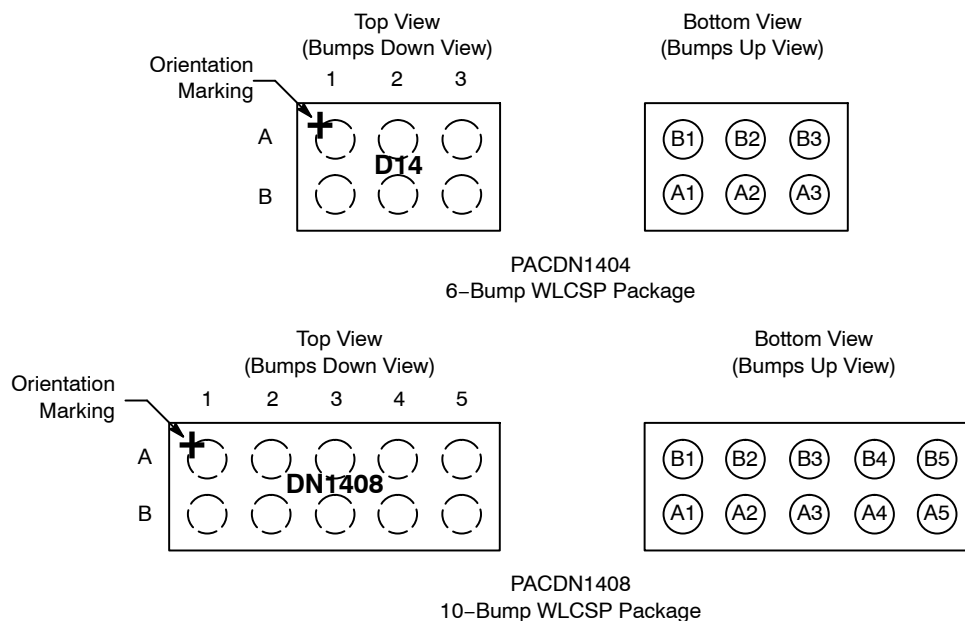
ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-------------|-------------------|-----------------------|
| PACDN1404CG | WLCSP6 (Pb-Free) | 3500/Tape & Reel |
| PACDN1408CG | WLCSP10 (Pb-Free) | 3500/Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

PACDN1404

PACKAGE / PINOUT DIAGRAMS



SPECIFICATIONS

Table 1. ABSOLUTE MAXIMUM RATINGS

| Parameter | Rating | Units |
|---------------------------|-------------|-------|
| Storage Temperature Range | -65 to +150 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 2. STANDARD OPERATING CONDITIONS

| Parameter | Rating | Units |
|-----------------------------|------------|-------|
| Operating Temperature Range | -40 to +85 | °C |

Table 3. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|------------|--|--------------------------|----------------------|-------------|-------------|-------|
| V_{REV} | Reverse Standoff Voltage | $I_{DIODE} = 10 \mu A$ | 5.5 | | | V |
| I_{LEAK} | Leakage Current | $V_{IN} = 3.3 V DC$ | | | 100 | nA |
| V_{SIG} | Signal Clamp Voltage Positive Clamp Negative Clamp | $I_{LOAD} = 10 mA$ | 5.6 -1.2 | 6.8 -0.8 | 8.0 -0.4 | V |
| V_{ESD} | In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4 | (Note 2) | ± 30 ± 25 | | | kV |
| V_{CL} | Clamping Voltage during ESD Discharge MIL-STD-883 (Method 3015), 8 kV Positive Transients Negative Transients | (Note 2) | | +12 -8 | | V |
| C | Channel Capacitance | At 2.5 V DC, $f = 1 MHz$ | | 39 | 47 | pF |

- $T_A = 25^\circ C$ unless otherwise specified. GND in this document refers to the lower supply voltage.
- ESD applied to channel pins with respect to GND, one at a time. All other channels are open. All GND pins tied to ground.

PACDN1404

APPLICATION INFORMATION

| Parameter | Value |
|--|------------------------------|
| Pad Size on PCB | 0.240 mm |
| Pad Shape | Round |
| Pad Definition | Non-Solder Mask Defined Pads |
| Solder Mask Opening | 0.290 mm Round |
| Solder Stencil Thickness | 0.125 mm – 0.150 mm |
| Solder Stencil Aperture Opening (Laser Cut, 5% Tapered Walls) | 0.300 mm Round |
| Solder Flux Ratio | 50/50 by Volume |
| Solder Paste Type | No Clean |
| Pad Protective Finish | OSP (Entek Cu Plus 106A) |
| Tolerance – Edge To Corner Ball | ±50 μm |
| Solder Ball Side Coplanarity | ±20 μm |
| Maximum Dwell Time Above Liquidous (183°C) | 60 seconds |
| Maximum Soldering Temperature for Lead-free Devices Using a Lead-free Solder Paste | 260°C |

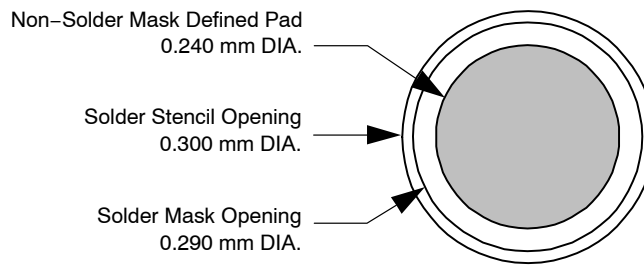


Figure 1. Recommended Non-Solder Mask Defined Pad Illustration

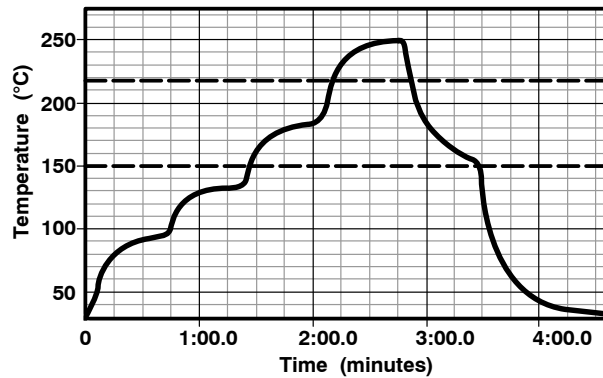


Figure 2. Lead-free (SnAgCu) Solder Ball Reflow Profile

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

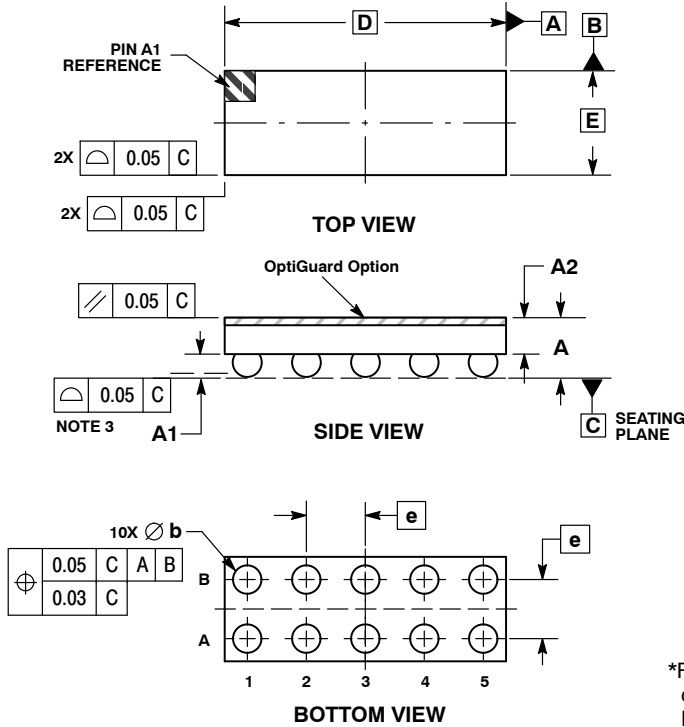
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WLCSP10, 3.10x1.15
CASE 567BM-01
ISSUE O

SCALE 4:1

DATE 26 JUL 2010

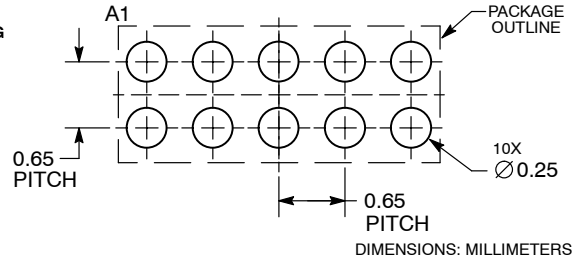


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | 0.60 | 0.75 |
| A1 | 0.23 | 0.29 |
| A2 | 0.40 REF | |
| b | 0.34 | 0.39 |
| D | 3.10 BSC | |
| E | 1.15 BSC | |
| e | 0.65 BSC | |

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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